11. (amended) Projection lens according to claim 8, wherein the first optical element and a second optical element of the sixth optical group enclose a gas chamber, wherein it holds for the radius of curvature R3 of the surface of the second optical element, which faces the first lens, that:

|R3| > 3000 mm.

- 12. (amended) Projection lens according to claim 11, wherein it holds for the radius of curvature R3 that: |R3| > 5000 mm.
- 13. (amended) Projection lens according to claim 11, wherein it holds for the radius of curvature R4 of the further surface of the second optical element that:

|R4| > 3000 mm, preferably |R4| > 5000 mm.

- 15. (amended) Projection lens according to claim 8, wherein a lens with an aspheric surface is provided in the first lens cluster.
- 17. (amended) Projection lens according to claim 15, wherein the aspheric surface is arranged on the first curved surface of the aspheric lens.
- 25. (amended) System for projection lens according to claim 19, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on a substrate, which is to be exposed, in the sixth optical group.
- 26. (amended) System for projection lens according to claim 20, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on a substrate, which is to be exposed, in a sixth optical group.

27. Contact 33

(amended) System for projection lens according to claim 21, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on a substrate, which is to be exposed, in a sixth optical group.

W 24.

(amended) Method according to claim 29, wherein when the projection lens is being tuned a filling gas is introduced which is subsequently exchanged by the operator for a gas mixture.

36. (1) and (3) and (3) and (amended) Method for producing microstructured components, in the case of which a substrate provided with a light-sensitive layer is exposed by ultraviolet light by means of a mask and a projection exposure machine according to claim 26 and is structured after the development of the light-sensitive layer in accordance with a pattern included on the mask.

Respectfully submitted,

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